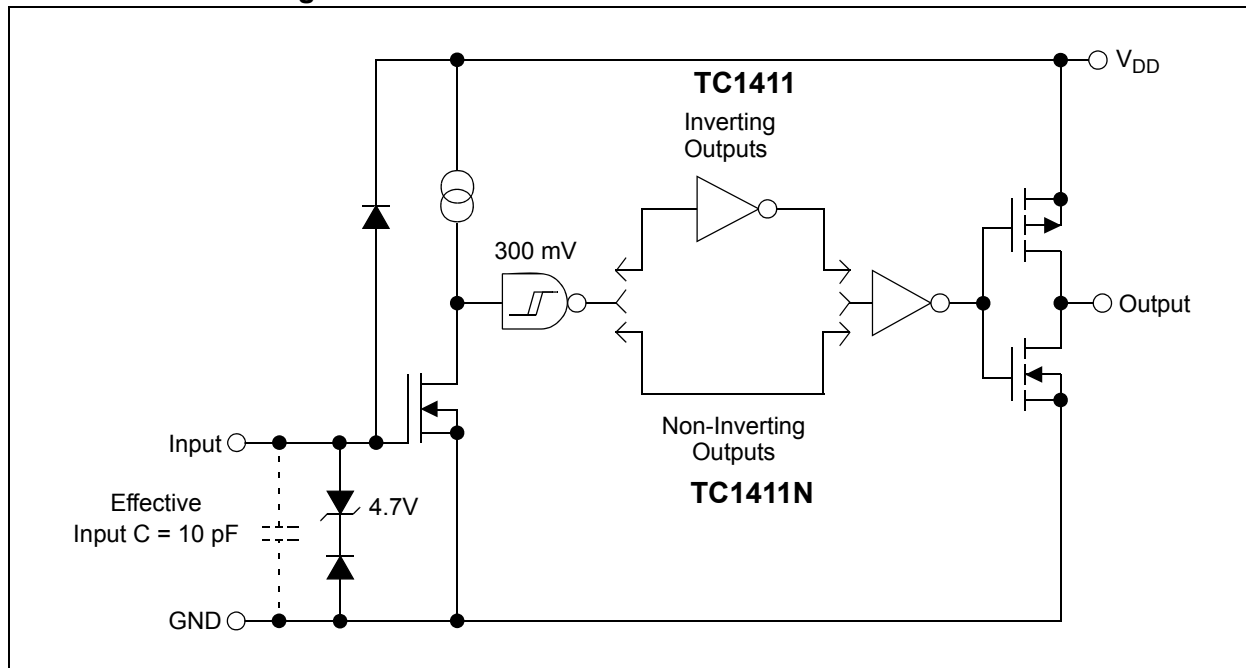


TC1411/TC1411N

Functional Block Diagram



1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings †

Supply Voltage	+20V
Input Voltage	$V_{DD} + 0.3V$ to GND – 5.0V
Power Dissipation ($T_A \leq 70^\circ\text{C}$)	
MSOP	340 mW
PDIP	730 mW
SOIC	470 mW
Storage Temperature Range	-65°C to +150°C
Maximum Junction Temperature	+150°C

† Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions above those indicated in the operation sections of the specifications is not implied. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability.

DC CHARACTERISTICS

Electrical Specifications: Unless otherwise noted, over operating temperature range with $4.5V \leq V_{DD} \leq 16V$. Typical values are measured at $T_A = +25^\circ\text{C}$, $V_{DD} = 16V$.

Parameters	Sym	Min	Typ	Max	Units	Conditions
Input						
Logic '1', High Input Voltage	V_{IH}	2.0	—	—	V	
Logic '0', Low Input Voltage	V_{IL}	—	—	0.8	V	
Input Current	I_{IN}	-1.0 -10	— —	1.0 10	μA	$0V \leq V_{IN} \leq V_{DD}$, $T_A = +25^\circ\text{C}$ $-40^\circ\text{C} \leq T_A \leq +85^\circ\text{C}$
Output						
High Output Voltage	V_{OH}	$V_{DD} - 0.025$	—	—	V	DC Test
Low Output Voltage	V_{OL}	—	—	0.025	V	DC Test
Output Resistance	R_O	— — —	8 10 10	11 14 14	Ω	$V_{DD} = 16V$, $I_O = 10\text{ mA}$, $T_A = +25^\circ\text{C}$ $0^\circ\text{C} \leq T_A \leq +70^\circ\text{C}$ $-40^\circ\text{C} \leq T_A \leq +85^\circ\text{C}$
Peak Output Current	I_{PK}	—	1.0	—	A	$V_{DD} = 16V$
Latch-Up Protection Withstand Reverse Current	I_{REV}	—	0.5	—	A	Duty cycle $\leq 2\%$, $t \leq 300\text{ }\mu\text{s}$, $V_{DD} = 16V$
Switching Time (Note 1)						
Rise Time	t_R	— — —	25 27 29	35 40 40	ns	$T_A = +25^\circ\text{C}$ $0^\circ\text{C} \leq T_A \leq +70^\circ\text{C}$ $-40^\circ\text{C} \leq T_A \leq +85^\circ\text{C}$, Figure 4-1
Fall Time	t_F	— — —	25 27 29	35 40 40	ns	$T_A = +25^\circ\text{C}$ $0^\circ\text{C} \leq T_A \leq +70^\circ\text{C}$ $-40^\circ\text{C} \leq T_A \leq +85^\circ\text{C}$, Figure 4-1
Delay Time	t_{D1}	— — —	30 33 35	40 45 45	ns	$T_A = +25^\circ\text{C}$, $0^\circ\text{C} \leq T_A \leq +70^\circ\text{C}$ $-40^\circ\text{C} \leq T_A \leq +85^\circ\text{C}$, Figure 4-1
Delay Time	t_{D2}	— — —	30 33 35	40 45 45	ns	$T_A = +25^\circ\text{C}$ $0^\circ\text{C} \leq T_A \leq +70^\circ\text{C}$ $-40^\circ\text{C} \leq T_A \leq +85^\circ\text{C}$, Figure 4-1
Power Supply						
Power Supply Current	I_S	— —	0.5 0.1	1.0 0.15	mA	$V_{IN} = 3V$, $V_{DD} = 16V$ $V_{IN} = 0V$

Note 1: Switching times ensured by design.

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TEMPERATURE CHARACTERISTICS

Electrical Specifications: Unless otherwise noted, all parameters apply with $4.5V \leq V_{DD} \leq 16V$.						
Parameters	Sym	Min	Typ	Max	Units	Conditions
Temperature Ranges						
Specified Temperature Range (C)	T_A	0	—	+70	°C	
Specified Temperature Range (E)	T_A	-40	—	+85	°C	
Specified Temperature Range (V)	T_A	-40	—	+125	°C	
Maximum Junction Temperature	T_J	—	—	+150	°C	
Storage Temperature Range	T_A	-65	—	+150	°C	
Package Thermal Resistances						
Thermal Resistance, 8L-MSOP	θ_{JA}	—	206	—	°C/W	
Thermal Resistance, 8L-PDIP	θ_{JA}	—	125	—	°C/W	
Thermal Resistance, 8L-SOIC	θ_{JA}	—	155	—	°C/W	

2.0 TYPICAL PERFORMANCE CURVES

Note: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

Note: Unless otherwise indicated, over operating temperature range with $4.5V \leq V_{DD} \leq 16V$.

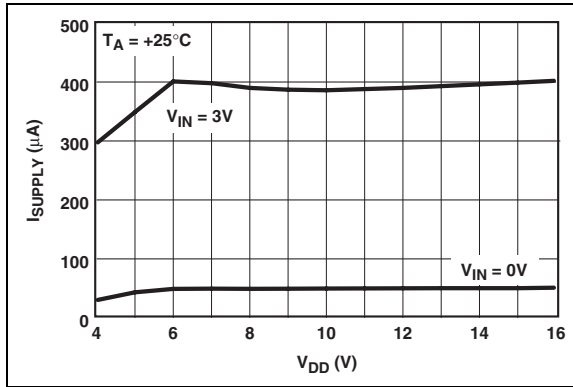


FIGURE 2-1: Quiescent Supply Current vs. Supply Voltage.

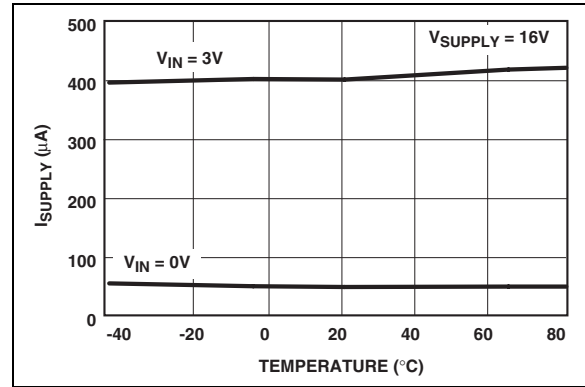


FIGURE 2-4: Quiescent Supply Current vs. Temperature.

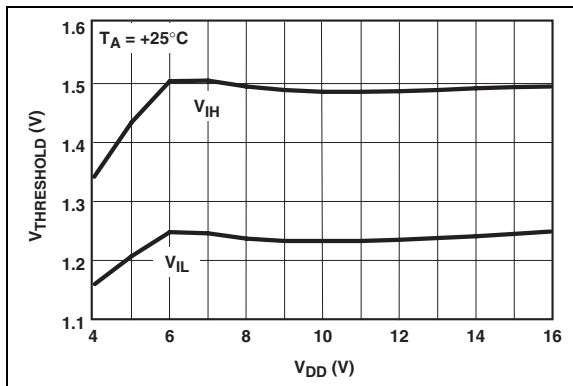


FIGURE 2-2: Input Threshold vs. Supply Voltage.

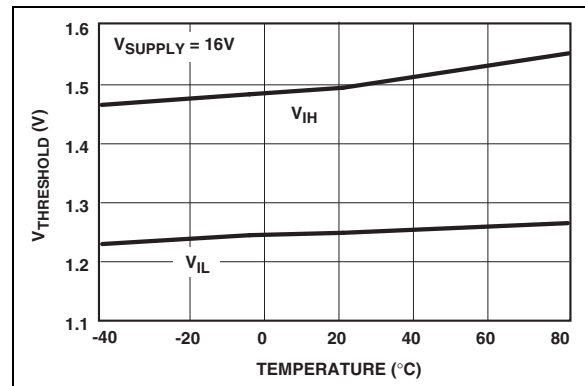


FIGURE 2-5: Input Threshold vs. Temperature.

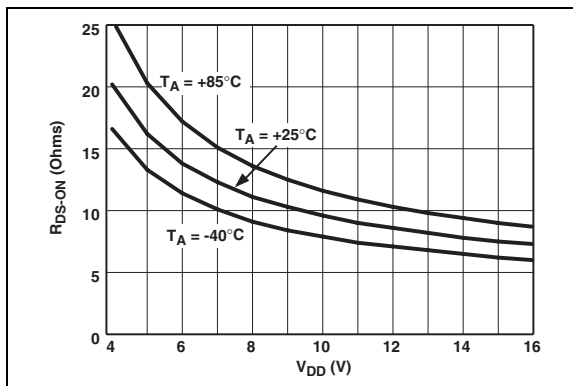


FIGURE 2-3: High-State Output Resistance vs. Supply Voltage.

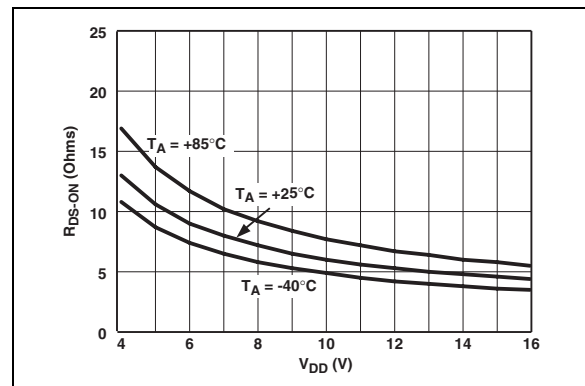


FIGURE 2-6: Low-State Output Resistance vs. Supply Voltage.

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Note: Unless otherwise indicated, over operating temperature range with $4.5V \leq V_{DD} \leq 16V$.

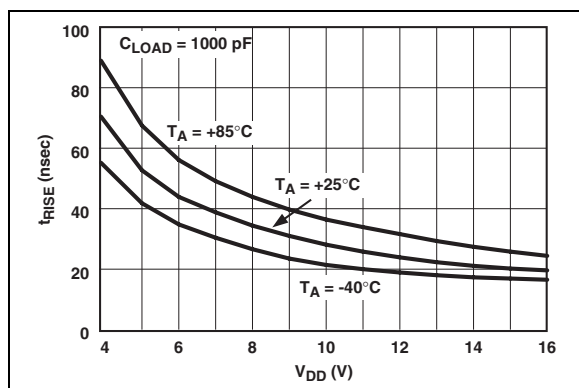


FIGURE 2-7: Rise Time vs. Supply Voltage.

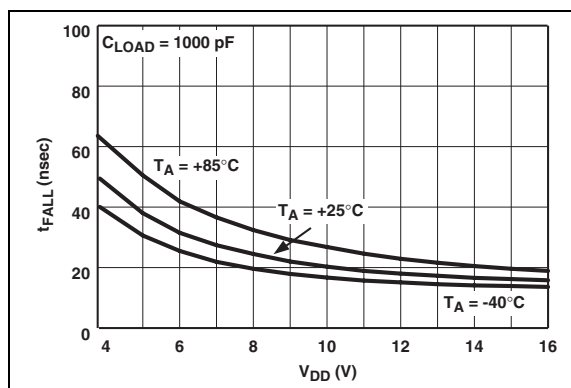


FIGURE 2-10: Fall Time vs. Supply Voltage.

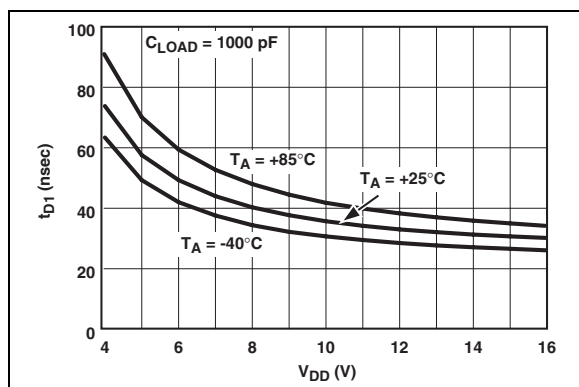


FIGURE 2-8: Propagation Delay vs. Supply Voltage.

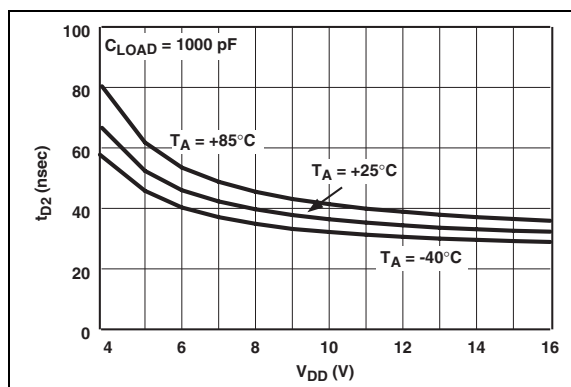


FIGURE 2-11: Propagation Delay vs. Supply Voltage.

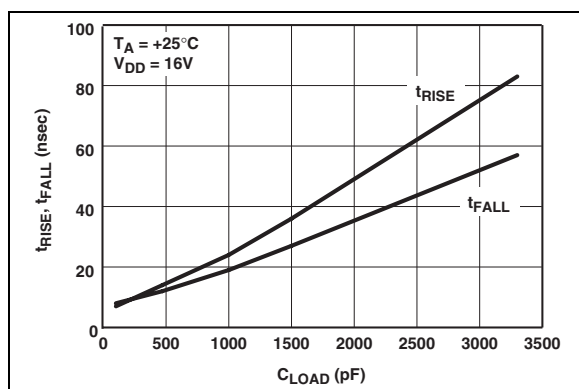


FIGURE 2-9: Rise and Fall Times vs. Capacitive Load.

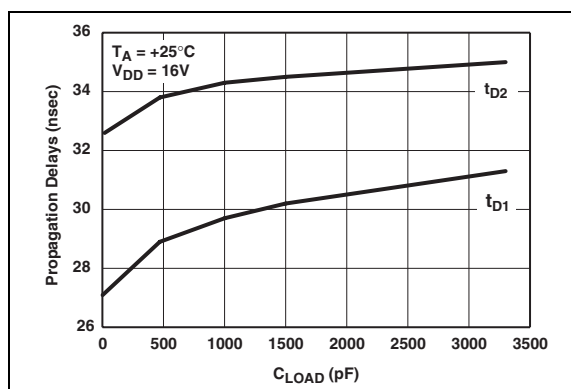


FIGURE 2-12: Propagation Delays vs. Capacitive Load.

3.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 3-1.

TABLE 3-1: PIN FUNCTION TABLE

Pin No.	Symbol	Description
1	V _{DD}	Supply input, 4.5V to 16V
2	INPUT	Control input
3	NC	No connection
4	GND	Ground
5	GND	Ground
6	OUTPUT	CMOS push-pull output, common to pin 7
7	OUTPUT	CMOS push-pull output, common to pin 6
8	V _{DD}	Supply input, 4.5V to 16V

3.1 Supply Input (V_{DD})

The V_{DD} input is the bias supply for the MOSFET driver and is rated for 4.5V to 16V with respect to the ground pin. The V_{DD} input should be bypassed to ground with a local ceramic capacitor. The value of the capacitor should be chosen based on the capacitive load that is being driven. A value of 1.0 μ F is suggested.

3.2 Control Input (INPUT)

The MOSFET driver input is a high-impedance, TTL/CMOS-compatible input. The input has 300 mV of hysteresis between the high and low thresholds that prevents output glitching even when the rise and fall time of the input signal is very slow.

3.3 CMOS Push-pull Output (OUTPUT)

The MOSFET driver output is a low impedance, CMOS push-pull style output, capable of driving a capacitive load with 1A peak currents.

3.4 Ground (GND)

The ground pins are the return path for the bias current and for the high peak currents which discharge the load capacitor. The ground pins should be tied into a ground plane or have very short traces to the bias supply source return.

3.5 No Connect (NC)

No internal connection.

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4.0 APPLICATION INFORMATION

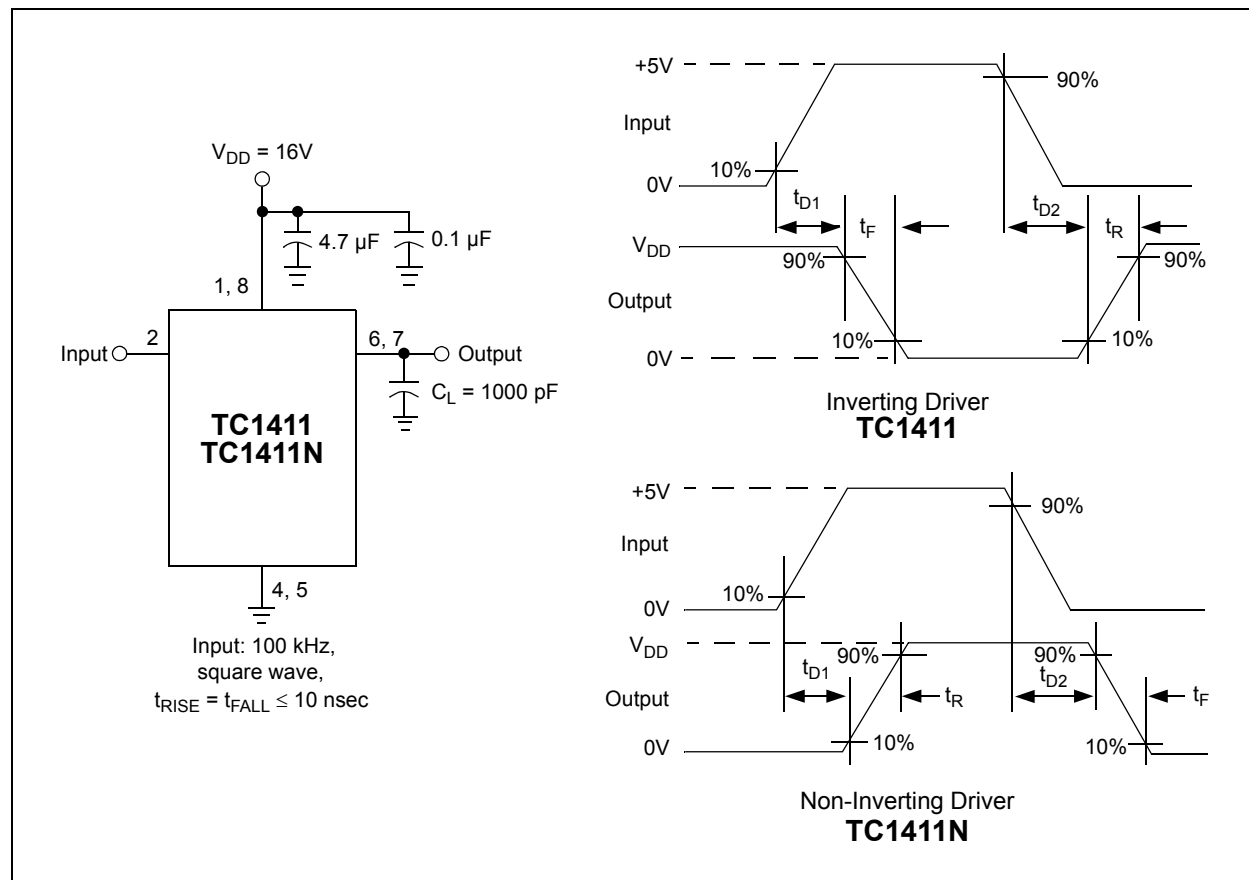
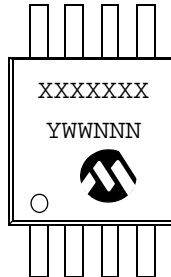


FIGURE 4-1: Switching Time Test Circuit.

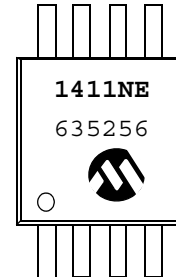
5.0 PACKAGING INFORMATION

5.1 Package Marking Information

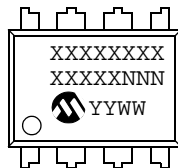
8-Lead MSOP



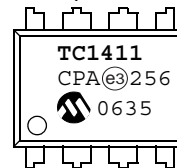
Example:



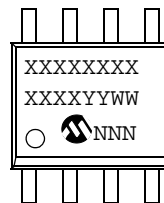
8-Lead PDIP (300 mil)



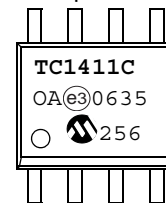
Example:



8-Lead SOIC (150 mil)



Example:



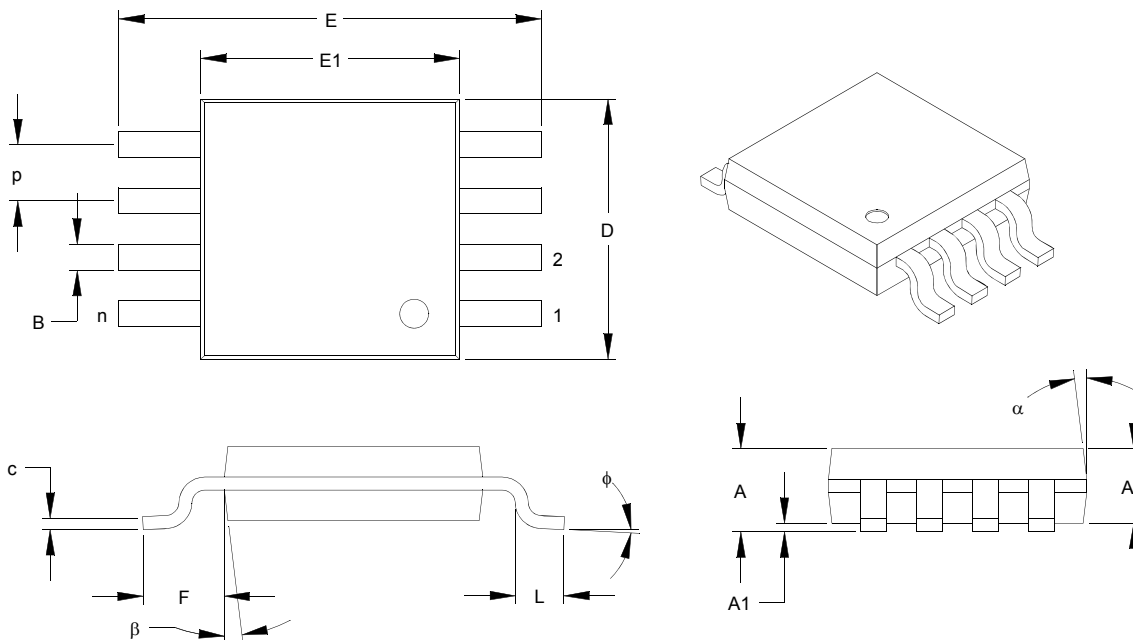
Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator ((e3)) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

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8-Lead Plastic Micro Small Outline Package (UA) (MSOP)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		INCHES			MILLIMETERS*		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	p	.026 BSC			0.65 BSC		
Overall Height	A	-	-	.043	-	-	1.10
Molded Package Thickness	A2	.030	.033	.037	0.75	0.85	0.95
Standoff	A1	.000	-	.006	0.00	-	0.15
Overall Width	E	.193 BSC			4.90 BSC		
Molded Package Width	E1	.118 BSC			3.00 BSC		
Overall Length	D	.118 BSC			3.00 BSC		
Foot Length	L	.016	.024	.031	0.40	0.60	0.80
Footprint (Reference)	F	.037 REF			0.95 REF		
Foot Angle	phi	0°	-	8°	0°	-	8°
Lead Thickness	c	.003	.006	.009	0.08	-	0.23
Lead Width	B	.009	.012	.016	0.22	-	0.40
Mold Draft Angle Top	alpha	5°	-	15°	5°	-	15°
Mold Draft Angle Bottom	beta	5°	-	15°	5°	-	15°

* Controlling Parameter

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

See ASME Y14.5M

REF: Reference Dimension, usually without tolerance, for information purposes only.

See ASME Y14.5M

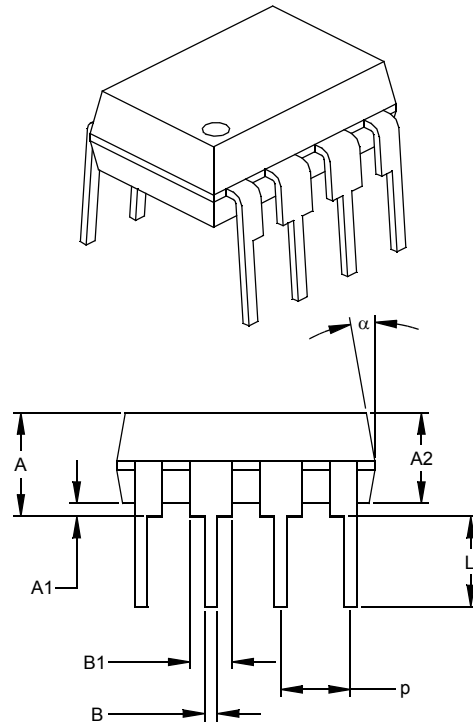
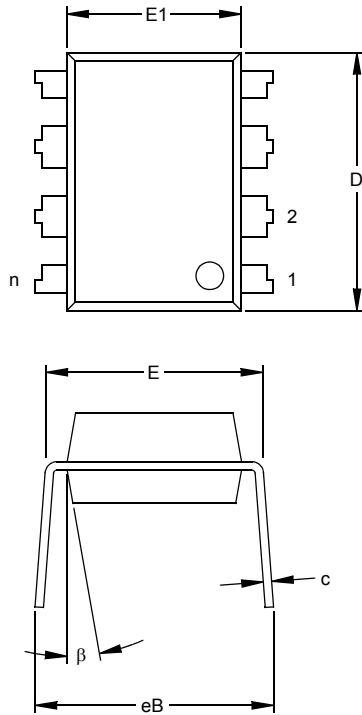
JEDEC Equivalent: MO-187

Drawing No. C04-111

Revised 07-21-05

8-Lead Plastic Dual In-line (PA) – 300 mil (PDIP)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n	8			8		
Pitch	p		.100			2.54	
Top to Seating Plane	A	.140	.155	.170	3.56	3.94	4.32
Molded Package Thickness	A2	.115	.130	.145	2.92	3.30	3.68
Base to Seating Plane	A1	.015			0.38		
Shoulder to Shoulder Width	E	.300	.313	.325	7.62	7.94	8.26
Molded Package Width	E1	.240	.250	.260	6.10	6.35	6.60
Overall Length	D	.360	.373	.385	9.14	9.46	9.78
Tip to Seating Plane	L	.125	.130	.135	3.18	3.30	3.43
Lead Thickness	c	.008	.012	.015	0.20	0.29	0.38
Upper Lead Width	B1	.045	.058	.070	1.14	1.46	1.78
Lower Lead Width	B	.014	.018	.022	0.36	0.46	0.56
Overall Row Spacing	§ eB	.310	.370	.430	7.87	9.40	10.92
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	β	5	10	15	5	10	15

* Controlling Parameter

§ Significant Characteristic

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

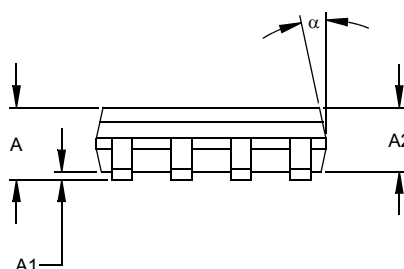
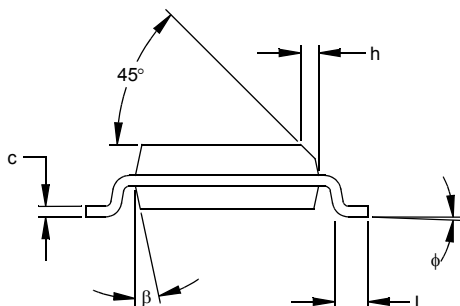
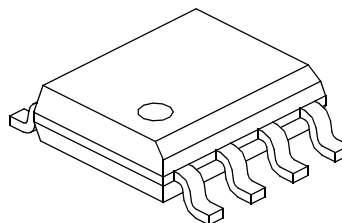
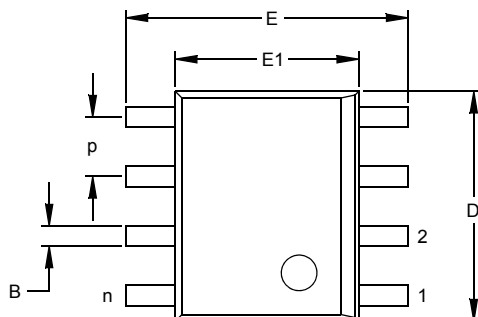
JEDEC Equivalent: MS-001

Drawing No. C04-018

TC1411/TC1411N

8-Lead Plastic Small Outline (OA) – Narrow, 150 mil (SOIC)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n	8			8		
Pitch	p		.050			1.27	
Overall Height	A	.053	.061	.069	1.35	1.55	1.75
Molded Package Thickness	A2	.052	.056	.061	1.32	1.42	1.55
Standoff §	A1	.004	.007	.010	0.10	0.18	0.25
Overall Width	E	.228	.237	.244	5.79	6.02	6.20
Molded Package Width	E1	.146	.154	.157	3.71	3.91	3.99
Overall Length	D	.189	.193	.197	4.80	4.90	5.00
Chamfer Distance	h	.010	.015	.020	0.25	0.38	0.51
Foot Length	L	.019	.025	.030	0.48	0.62	0.76
Foot Angle	φ	0	4	8	0	4	8
Lead Thickness	c	.008	.009	.010	0.20	0.23	0.25
Lead Width	B	.013	.017	.020	0.33	0.42	0.51
Mold Draft Angle Top	α	0	12	15	0	12	15
Mold Draft Angle Bottom	β	0	12	15	0	12	15

* Controlling Parameter

§ Significant Characteristic

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: MS-012

Drawing No. C04-057

APPENDIX A: REVISION HISTORY

Revision D (September 2006)

- Added -40°C to +125°C temperature range to Temperature Characteristics table and Product Information System page.
- Added disclaimer to package outline drawings.

Revision C (March 2003)

- Added 8-Lead MSOP Package.

Revision B (May 2002)

- Converted TELCOM data sheet for Embedded Control Handbook

Revision A (March 2001)

- Original Release of this Document.

TC1411/TC1411N

NOTES:

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

<u>PART NO.</u>	<u>X</u>	<u>/XX</u>
Device	Temperature Range	Package
Device: TC1411: 1 A Single MOSFET Driver, Inverting TC1411N: 1 A Single MOSFET Driver, Non-Inverting Temperature Range: C = 0°C to +70°C E = -40°C to +85°C V = -40°C to +125°C Package: OA = Plastic SOIC, (150 mil Body), 8-lead OA713 = Plastic SOIC, (150 mil Body), 8-lead (Tape and Reel) UA = Plastic Micro Small Outline (MSOP), 8-lead * UA713 = Plastic Micro Small Outline (MSOP), 8-lead * (Tape and Reel) PA = Plastic DIP (300 mil Body), 8-lead * MSOP package is only available in E-Temp.		
Examples: a) TC1411COA: 1A Single MOSFET driver, 8LD SOIC pkg, 0°C to +70°C. b) TC1411CPA: 1A Single MOSFET driver, 8LD PDIP package, 0°C to +70°C. c) TC1411EUA713: Tape and Reel, 1A Single MOSFET driver, 8LD MSOP package, -40°C to +85°C. d) TC1411VOA713: Tape and Reel, 1A Single MOSFET driver, 8LD SOIC pkg, -40°C to +125°C. a) TC1411NCPA: 1A Single MOSFET driver, 8LD PDIP package, 0°C to +70°C. b) TC1411NEPA: 1A Single MOSFET driver, 8LD PDIP package, -40°C to +85°C. c) TC1411NEUA: 1A Single MOSFET driver, 8LD MSOP package, -40°C to +85°C. d) TC1411NVPA: 1A Single MOSFET driver, 8LD PDIP package, -40°C to +125°C.		

TC1411/TC1411N

NOTES:

Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
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